







(0.80 mm) .0315"

SEAM8 SERIES

ULTRA-HIGH DENSITY OPEN-PIN-FIELD

SPECIFICATIONS For complete specifications and

recommended PCB layouts see www.samtec.com?SEAM8

Insulator Material: Black LCP

Contact Material: Copper Alloy Plating:

Au or Sn over 50 μ" (1.27 μm) Ni Operating Temp Range: -55 °C to +125 °C Current Rating:

.3 A per pin (10 adjacent pins powered)
Working Voltage:

RoHS Compliant:

Yes Lead-Free Solderable:

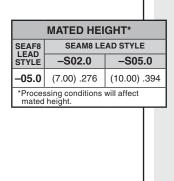
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

· Other pin counts



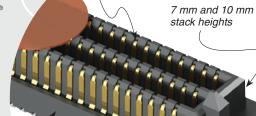
Notes: Patent Pending

Tape & Reel packaging is standard.

Some sizes, styles and options are non-standard, non-returnable.







Up to 500 I/Os

4, 6, 8 and 10 rows

Signal Integrity optimized Edge Rate® contact

Lead-Free solder charge terminations HIGH-SPEED CHANNEL PERFORMANCE

SEAM8/SEAF8 @ 7 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

PAM4

–10, –20,

30, -40, -50

(Standard sizes)

SEAM8

(0.75)

.029

NO. OF Α **ROWS** (4.30) .169 -04 (6.30)-06 .248 (8.30) -08 (10.30)-10

NO. PINS

PER ROW

S02.0 = 2 mm **Body**

LEAD

STYLE

S05.0 = 5 mm Body Height

= 10 µ" (0.25 µm) Gold on ontact area Matte Tin on solder tail

PLATING

OPTION

-S = 30 µ" (0.76 µm) Gold on contact area Matte Tin on solder tail

-04= Four Solder Rows Charge -06= Six Rows

NO. OF

ROWS

-08

= Eight

Rows

-10

= Ten

Rows

∙2 Lead-Free

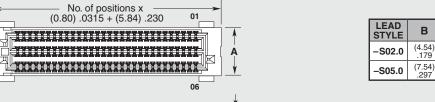
SOLDER

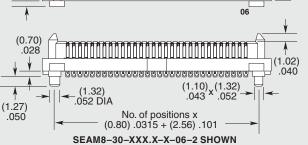
TYPE

-GP = Guide Post (-S02.0 lead style only) SÈAF8-RA-GP

OPTION

= Polyimide film Pick & Place Pad





Due to technical progress, all designs, specifications and components are subject to change without notice